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(12) **United States Design Patent** (10) **Patent No.:** **US D922,547 S**  
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(54) **SEAL MEMBERS FOR USE IN SEMICONDUCTOR PRODUCTION APPARATUSES**

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**Related U.S. Application Data**

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(58) **Field of Classification Search**  
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D23/269, 386, 259; D8/349;  
277/602-626; 285/95, 109, 336, 910, 918  
CPC ..... F16K 51/02; F16J 15/025; F16J 15/0887;  
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See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a seal member for use in semiconductor production apparatuses, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of a seal member for use in semiconductor production apparatuses, showing our new design;  
FIG. 2 is a front elevation view thereof;  
FIG. 3 is a rear elevation view thereof;  
FIG. 4 is a left side elevation view thereof;  
FIG. 5 is a right side elevation view thereof;  
FIG. 6 is a top view thereof;  
FIG. 7 is a bottom view thereof;  
FIG. 8 is a cross-sectional view thereof; and,  
FIG. 9 is an enlarged cross-sectional view of a portion thereof.

**1 Claim, 9 Drawing Sheets**



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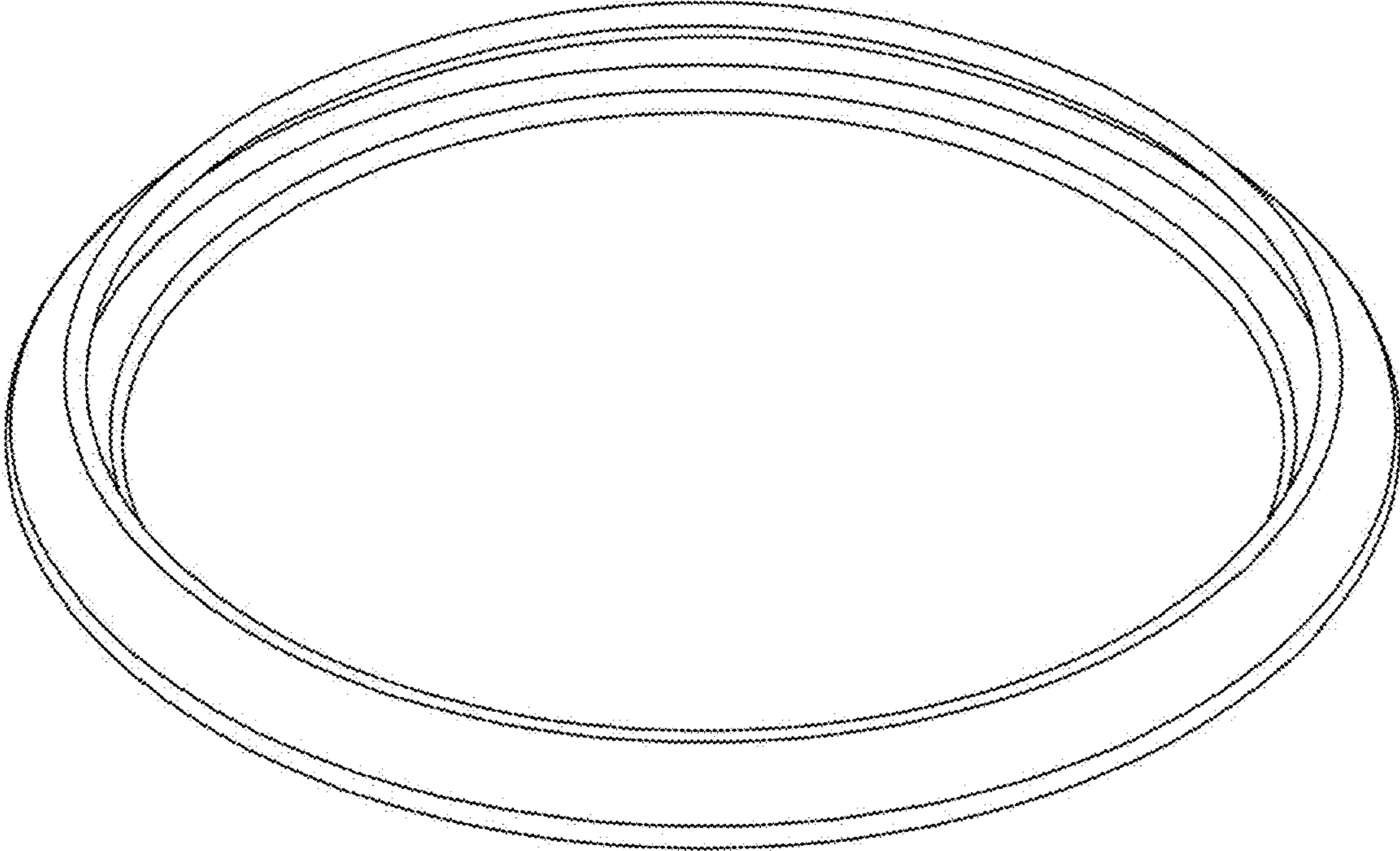
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**FIG. 1**



**FIG. 2**



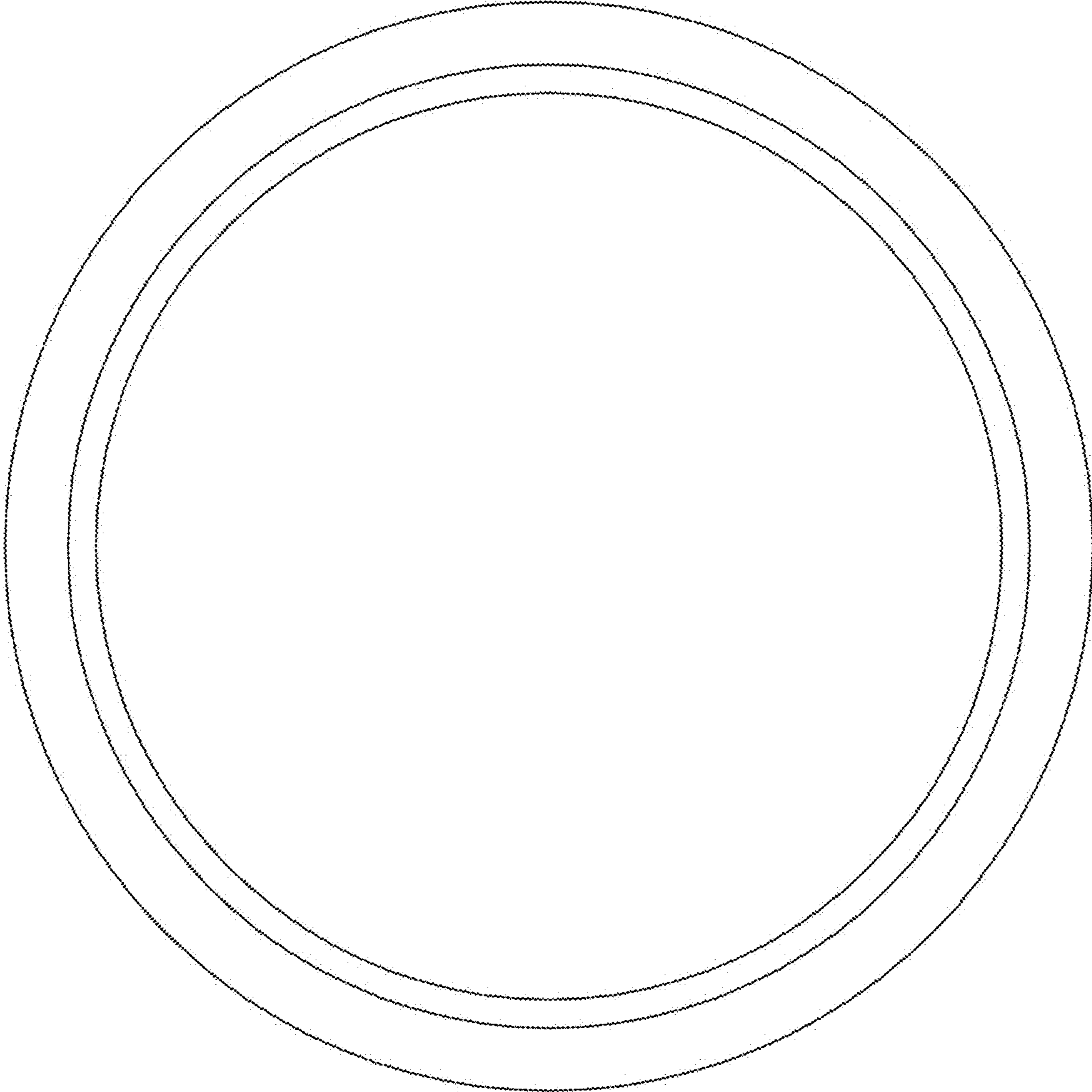
**FIG. 3**



**FIG. 4**

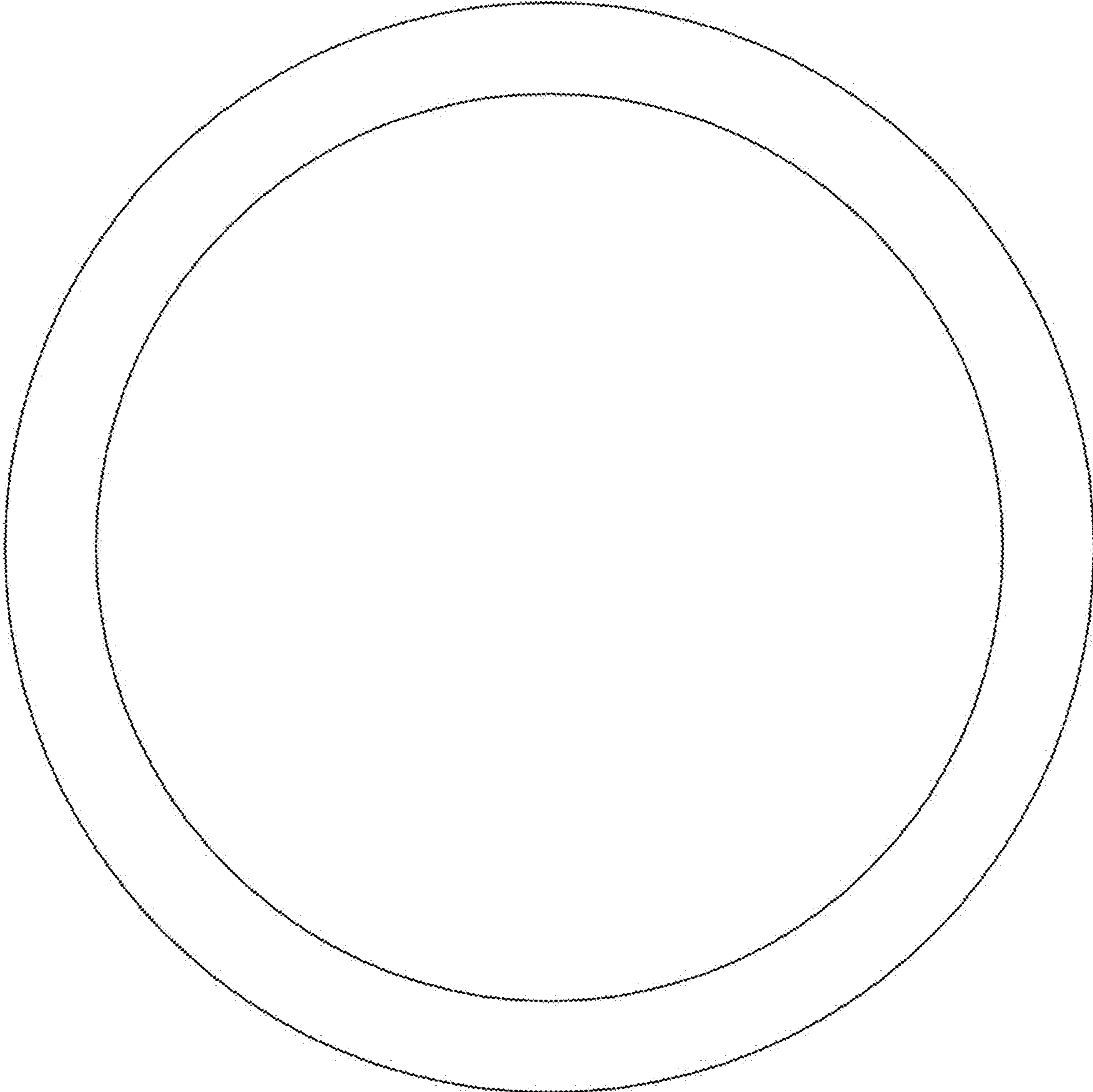


**FIG. 5**



**FIG. 6**





**FIG. 7**



FIG. 8

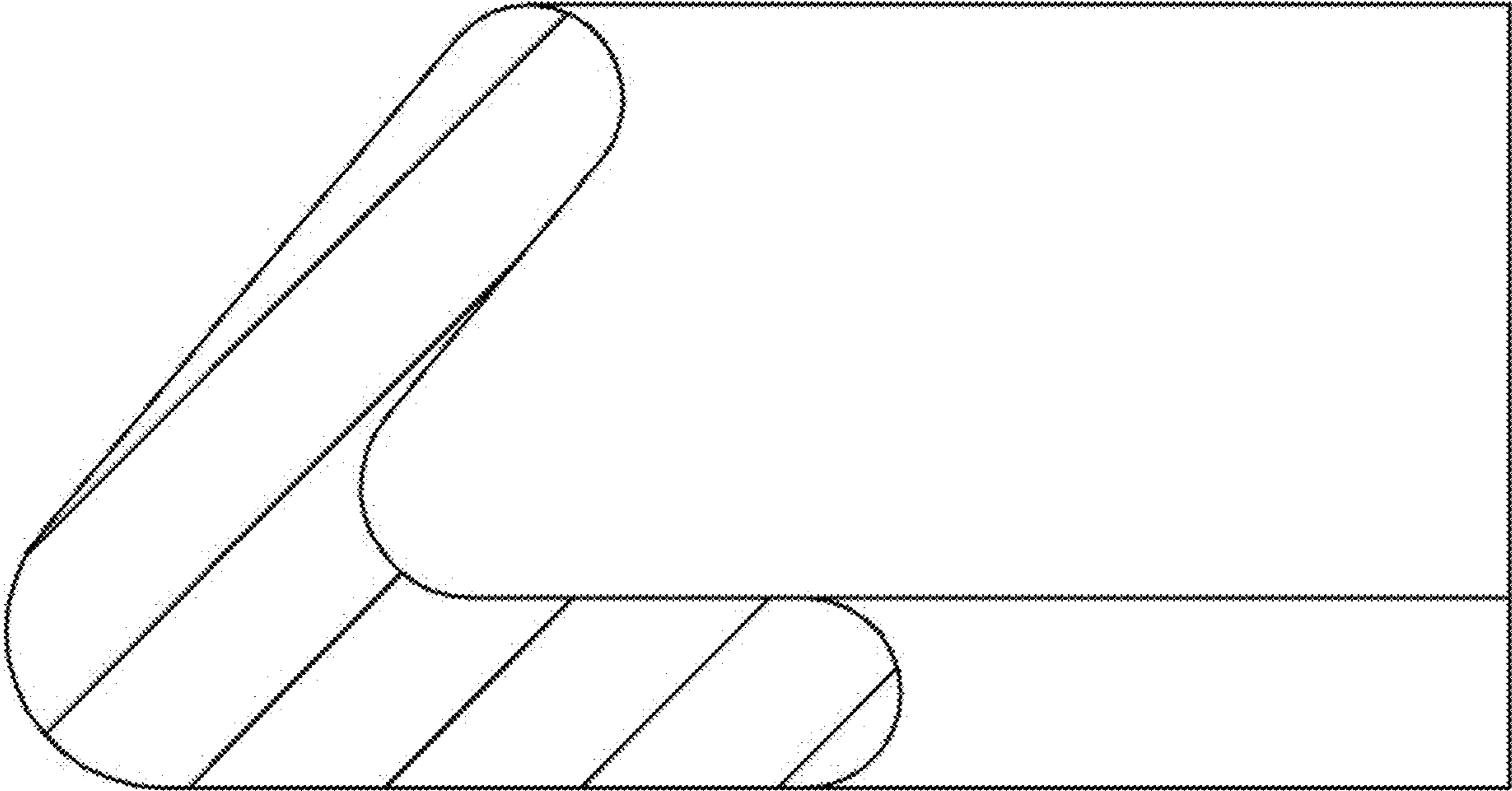


FIG. 9